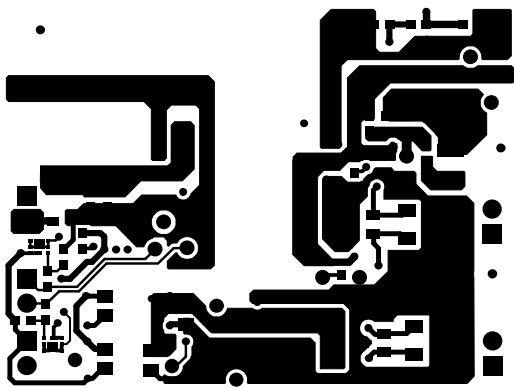
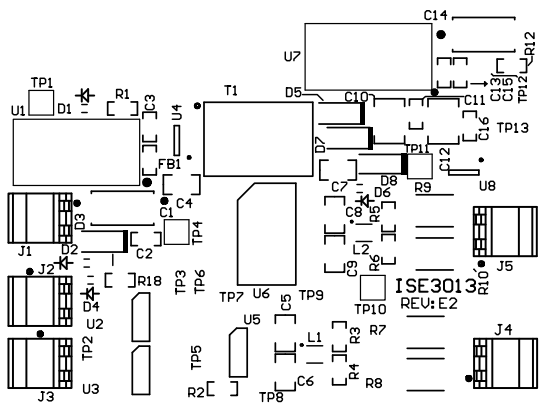


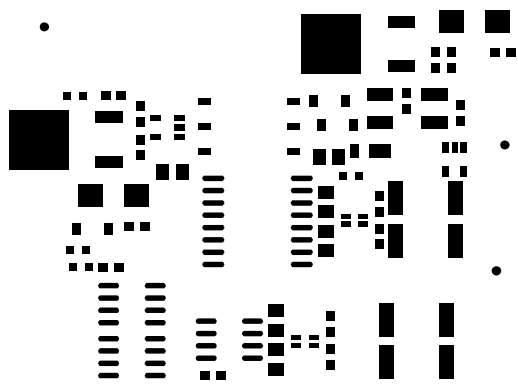
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LAYER NAME = Top Layer	ISE3013		
PLOT NAME = RS485_ADAPTOR_E2.GTL	GENERATED : 9/9/2014	1:30:01 PM	TEXAS INSTRUMENTS



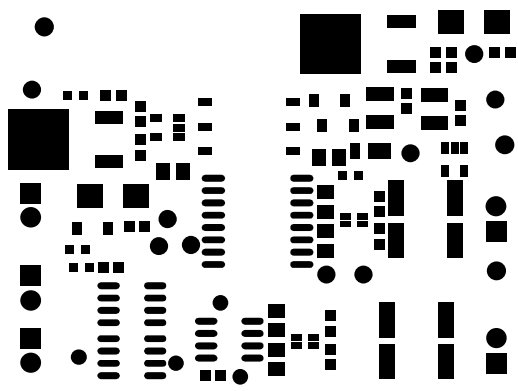
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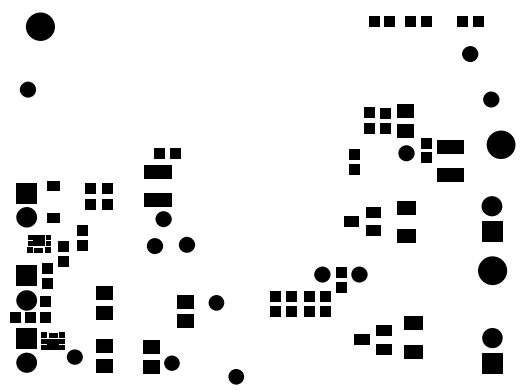
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LAYER NAME = Top Overlay	ISE3013		
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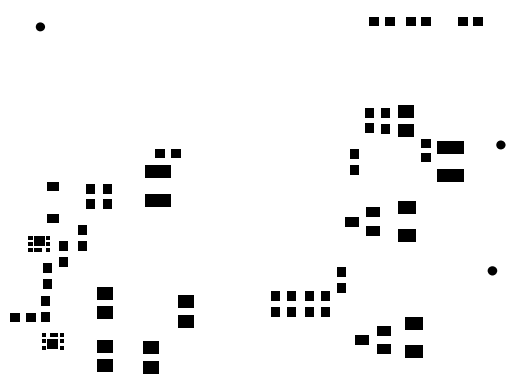
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LAYER NAME = Top Paste	ISE3013		
PLOT NAME = RS485_ADAPTOR_E2.GTP	GENERATED : 9/9/2014	1:30:01 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00308	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	ISE3013		
PLOT NAME = RS485_ADAPTOR_E2.GTS	GENERATED : 9/9/2014	1:30:01 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00308	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	ISE3013		
PLOT NAME = RS485_ADAPTOR_E2.GBS	GENERATED : 9/9/2014	1:30:01 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00308	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Paste	ISE3013		
PLOT NAME = RS485_ADAPTOR_E2.GBP	GENERATED : 9/9/2014	1:30:02 PM	TEXAS INSTRUMENTS







ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00308	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = OUTLINE	ISE3013		
PLOT NAME = RS485_ADAPTOR_E2.GM1	GENERATED : 9/9/2014	1:30:02 PM	TEXAS INSTRUMENTS

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